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AUG 30 2007

Appl. No. 10/815,164  
Response Dated August 30, 2007  
Reply to Office Action of May 31, 2007

**Pending Claims:**

This listing will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim 1 (Currently amended): A metal laminate manufactured by laminating a single layer of a polyimide copolymer to a metallic foil which metal laminate is subjected to an etching process to remove a portion of the metallic foil said etching process being conducted after the single layer of the polyimide copolymer is laminated to the metallic foil, process; said polyimide copolymer comprising two kinds of tetracarboxylic acid dianhydrides consisting of (A) isopropylidenebis (4-phenyleneoxy-4-phthalic acid) dianhydride and (B) 3,3', 4,4' -biphenyltetracarboxylic acid dianhydride, and (C) 6-amino-2-(p-aminophenyl)- benzimidazole and said polyimide copolymer being resistant to curling resulting from the metal laminate etching process so that the resulting etched metal laminate is substantially curl-free.

Claim 2 (Previously presented): A metal laminate according to claim 1, wherein the copolymer has a film formability.

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Claim 3 (Previously presented): A metal laminate according to Claim 1, wherein the two kinds of tetracarboxylic acid dianhydrides are used in a proportion of component (A) to component (B) of 10 – 80 mol.% to 90 – 20 mol.%.

Claim 4 (Canceled)

Claim 5 (Canceled):

Claim 6 (Previously presented): A metal laminate according to Claim 1 for use as a flexible printed circuit board.

Claim 7 (Currently amended): A metal laminate manufactured by laminating a single layer of a polyimide copolymer to a metallic foil which metal laminate is subjected to an etching process to remove a portion of the metallic foil said etching process being conducted after the single layer of the polyimide copolymer is laminated to the metallic foil, processes; said polyimide copolymer comprising two kinds of tetracarboxylic acid dianhydrides consisting of (A) isopropylidenebis (4-phenyleneoxy-4-phthalic acid) dianhydride and (B) 3,3', 4, 4' -biphenyltetracarboxylic acid dianhydride, and two or three kinds of diamines consisting of (C) 6-amino-2-(p-aminophenyl) benzimidazole and (D) at least one kind of diamines consisting of bis(4-aminophenyl) ether (D<sub>1</sub>) and phenylenediamine (D<sub>2</sub>) and said polyimide copolymer being resistant to curling resulting

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from the metal laminate etching process so that the resulting etched metal laminate is substantially curl-free.

Claim 8 (Previously presented): A metal laminate according to Claim 7, wherein the copolymer has a film formability.

Claim 9 (Previously presented): A metal laminate according to Claim 7, wherein the two kinds of tetracarboxylic acid dianhydrides are used in a proportion of component (A) to component (B) of 10 – 80 mol% to 90 – 20 mol% and the diamines are used in a proportion of component (C) to component (D<sub>1</sub>) of not less than 60 mol.% to not more than 40 mol.%.

Claim 10 (Previously presented): A metal laminate according to Claim 7, wherein the two kinds of tetracarboxylic acid dianhydrides are used in a proportion of component (A) to component (B) of 10 – 80 mol% to 90 – 20 mol.%, and the diamines are used in a proportion of component (C) to component (D<sub>2</sub>) of not less than 20 mol.% to not more than 80 mol.%.

Claims 11-14 (Canceled)

Claim 15 (Previously presented): A metal laminate according to Claim 7 for use as a flexible printed circuit board.

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Claim 16 (Canceled)

Claim 17 (Currently amended): A process for manufacturing a metal laminate laminated with a single polyimide copolymer layer, said process comprising the steps of:

- a) subjecting two kinds of tetracarboxylic acid dianhydrides consisting of (A) isopropylidenebis (4-phenyleneoxy-4-phthalic acid) dianhydride and (B) 3,3', 4,4' - biphenyltetracarboxylic acid dianhydride to reaction with one kind of diamine consisting of (C) 6-amino-2-(p-aminophenyl) benzimidazole or two or three kinds of diamines consisting of component (C) and (D) at least one kind of diamines consisting of bis(4-aminophenyl) ether (D<sub>1</sub>) and phenylenediamine (D<sub>2</sub>) in a polar solvent to form a solution of polyamic acid;
- b) applying the resulting solution of polyamic acid in the polar solvent from step a) to a metallic foil;
- c) drying the solvent off and heating the polyamic acid to a polyimidization reaction temperature to form a metal laminate; and
- d) subjecting the metal laminate to an etching process in which a portion of the metallic foil is etched and in which the polyimide copolymer layer resists and does not exhibit curling.